

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

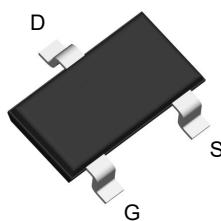
Product Summary



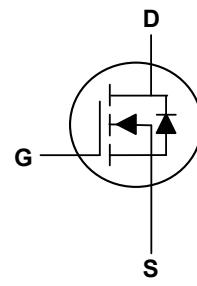
V_{DS}	20	V
I_D	4	A
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	45	mΩ
$R_{DS(ON)}$ (at $V_{GS}=2.5V$)	59	mΩ

Applications

- High Frequency Point-of-Load,Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch



SOT23 Top View



Absolute Maximum Ratings($T_A=25^\circ C$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ¹	I_D	4	A
Pulsed Drain Current ²	I_{DM}	10	A
Total Power Dissipation ³	P_D	1	W
Storage Temperature Range	T_{STG}	-55 to 150	°C
Operating Junction Temperature Range	T_J	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	---	125	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=250\mu\text{A}$	20	---	---	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=2.9\text{A}$	---	30	45	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$, $I_{\text{D}}=2.5\text{A}$	---	37	59	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=250\mu\text{A}$	0.5	0.85	1.2	V
Drain-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 12\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
Forward Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}$, $I_{\text{D}}=2.9\text{A}$	---	8	---	S
Total Gate Charge	Q_g	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=2.9\text{A}$	---	4	---	nC
Gate-Source Charge	Q_{gs}		---	0.65	---	
Gate-Drain Charge	Q_{gd}		---	1.2	---	
Turn-On Delay Time	$T_{\text{d}(\text{on})}$	$V_{\text{DD}}=10\text{V}$, $R_G=6\Omega$, $V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=2.9\text{A}$	---	10	---	ns
Rise Time	T_r		---	50	---	
Turn-Off Delay Time	$T_{\text{d}(\text{off})}$		---	17	---	
Fall Time	T_f		---	10	---	
Input Capacitance	C_{iss}	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	300	---	pF
Output Capacitance	C_{oss}		---	120	---	
Reverse Transfer Capacitance	C_{rss}		---	80	---	

Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current ²	I_s	$V_G=V_D=0\text{V}$, Force Current	---	---	4	A
Diode Forward Voltage ¹	V_{SD}	$V_{\text{GS}}=0\text{V}$, $I_s=2.9\text{A}$, $T_J=25^\circ\text{C}$	---	0.75	1.2	V

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature

Typical Characteristics

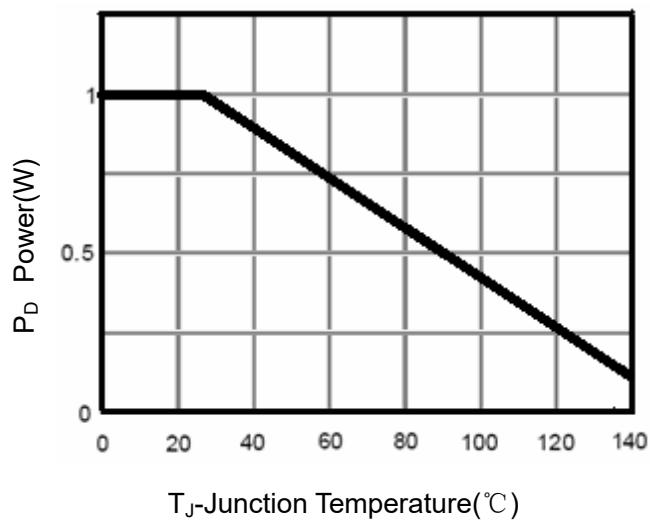


Figure 1 Power Dissipation

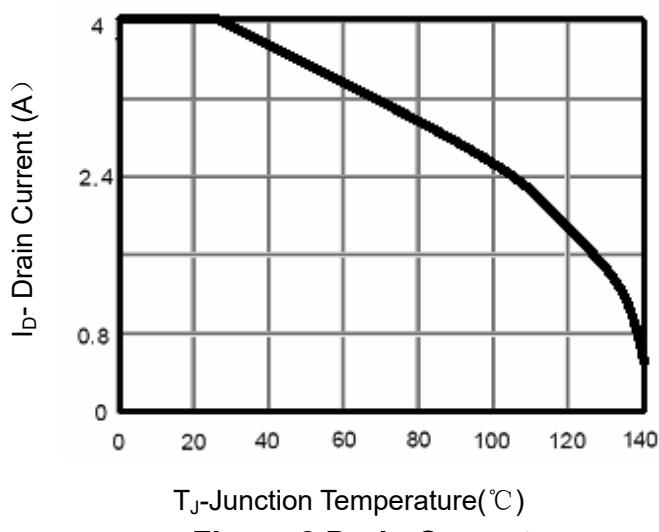


Figure 2 Drain Current

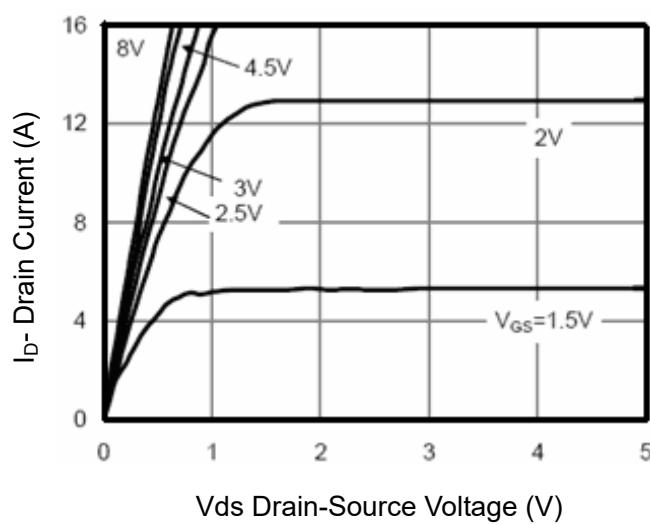


Figure 3 Output Characteristics

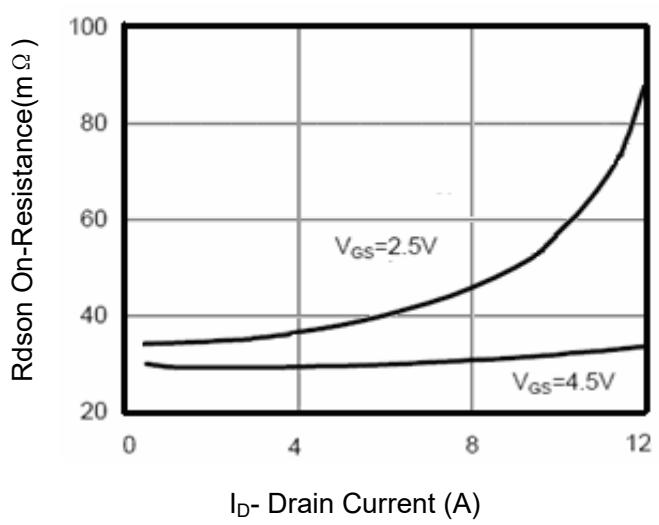


Figure 4 Drain-Source On-Resistance

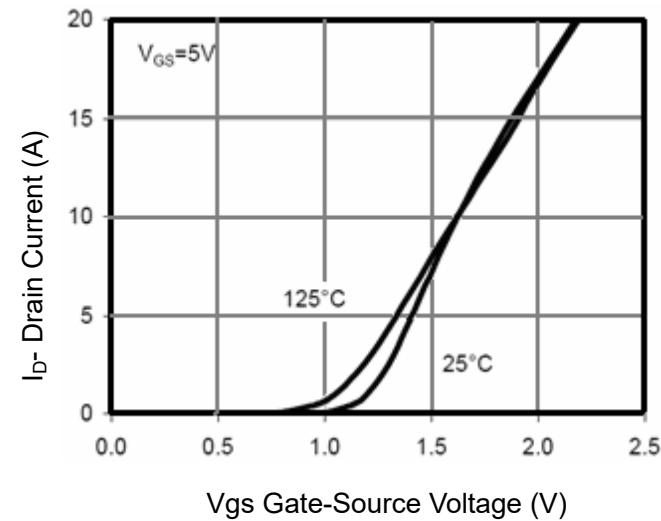


Figure 5 Transfer Characteristics

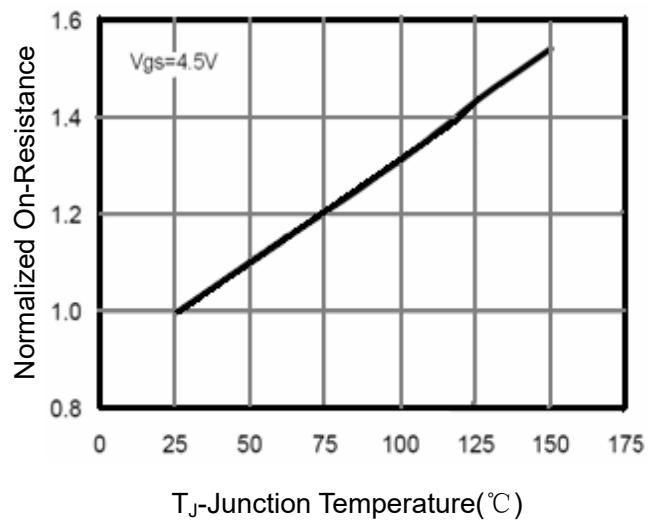


Figure 6 Drain-Source On-Resistance

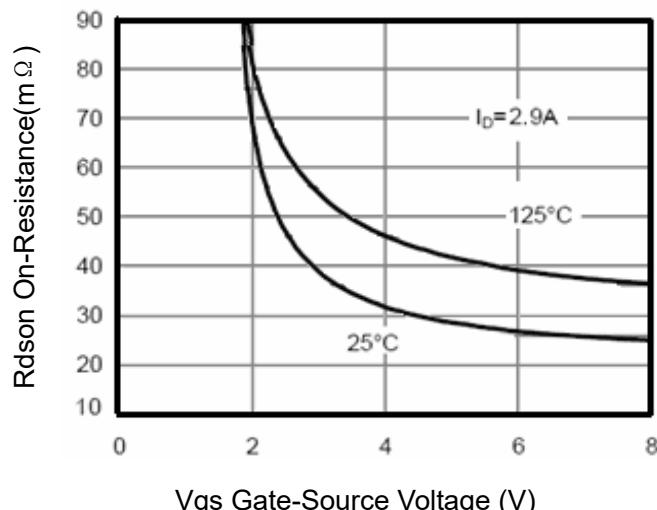


Figure 7 $R_{DS(on)}$ vs V_{GS}

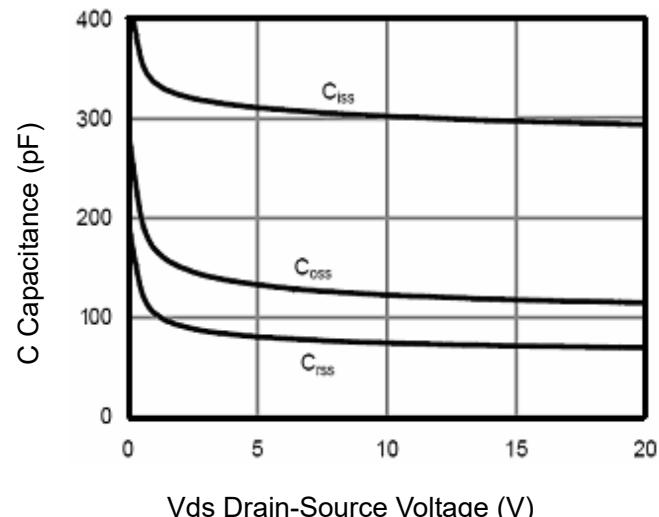


Figure 8 Capacitance vs V_{DS}

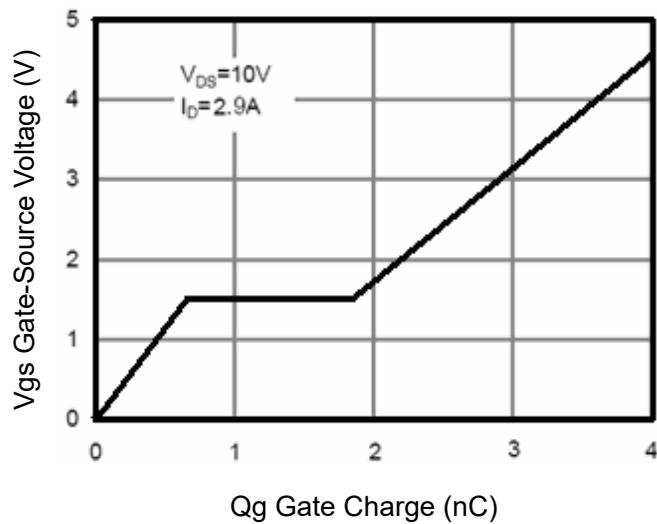


Figure 9 Gate Charge

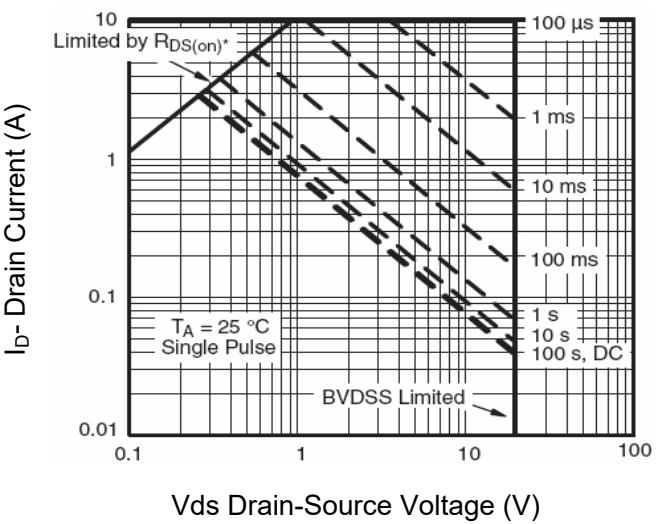


Figure 10 Safe Operation Area

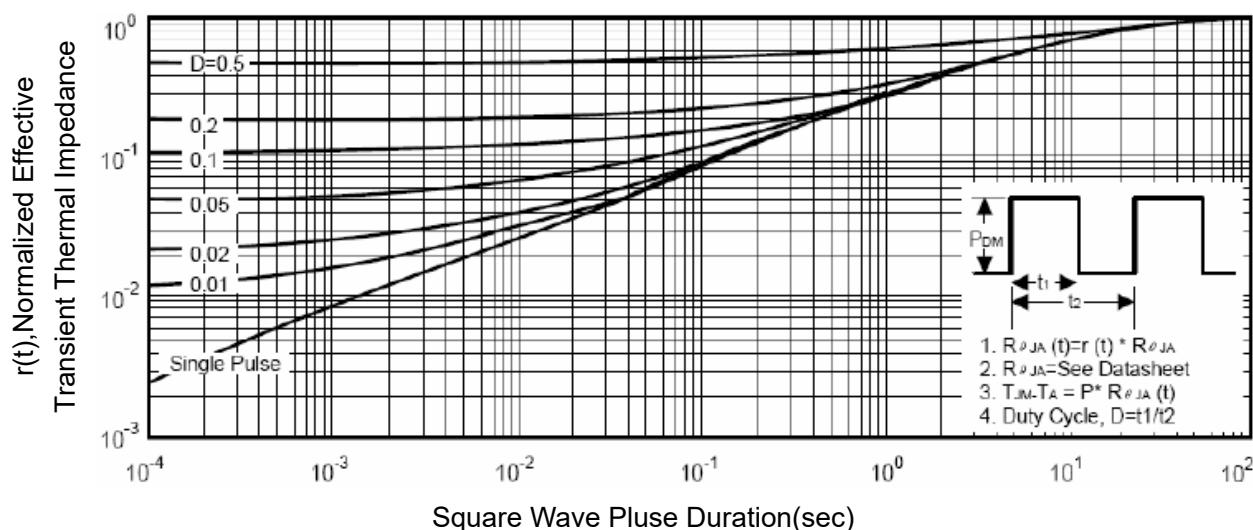
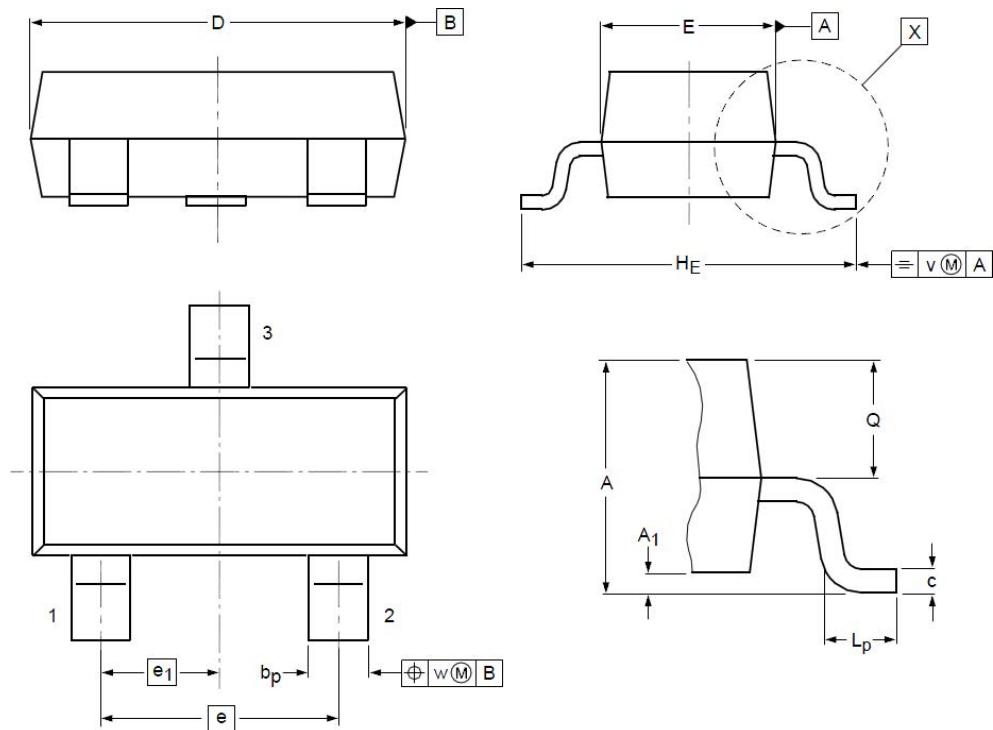


Figure 11 Normalized Maximum Transient Thermal Impedance

SOT23 Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.90	1.05	1.20	e₁	--	0.95	--
A₁	0.01	0.05	0.10	H_E	2.10	2.40	2.50
b_p	0.38	0.42	0.48	L_p	0.40	0.50	0.60
c	0.09	0.13	0.15	Q	0.45	0.49	0.55
D	2.80	2.92	3.00	V	--	0.20	--
E	1.20	1.33	1.40	W	--	0.10	--
e	--	1.90	--				